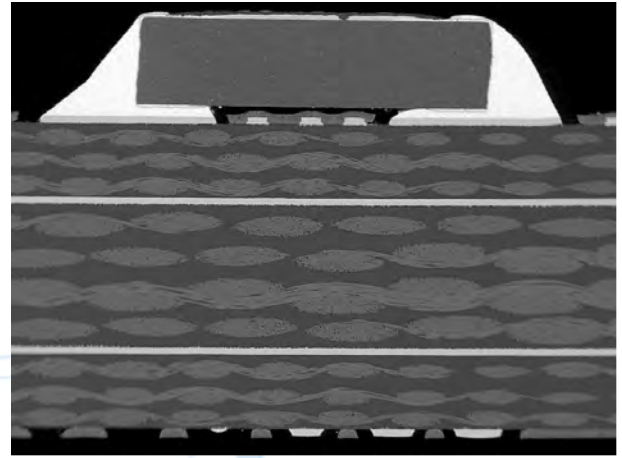
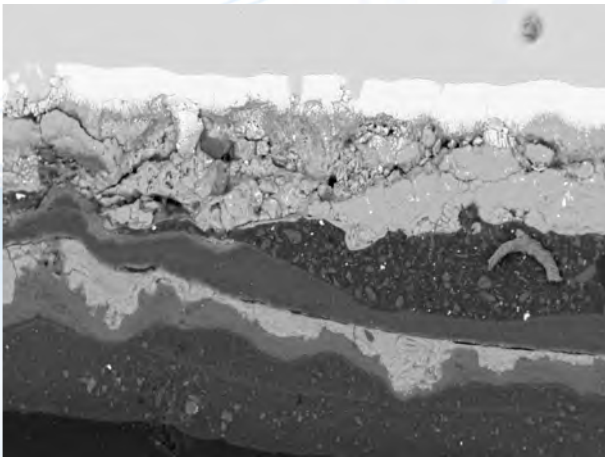


CROSS SECTIONING AND MATERIALS POLISHING

Many manufactured materials, as simple as laminated wood surfaces or as intricate as an integrated circuit package, will require custom preparation in order to analyze a sample. Cross sectioning allows for the preparation of a sample in order to expose specific features for analysis. MicroVision Labs can prepare a wide variety of materials with precision cross sectioning and polishing services in order to allow these features to be presented. Materials can be mounted and embedded in a variety of epoxies and polymer compounds in order to stabilize and enforce materials. Materials can then be sectioned with a diamond saw or microtome, and polished in order to smooth any cutting artifacts. Precise depths of sectioning can be maintained, in order to highlight specific areas of interest.



Printed Circuit Board Components



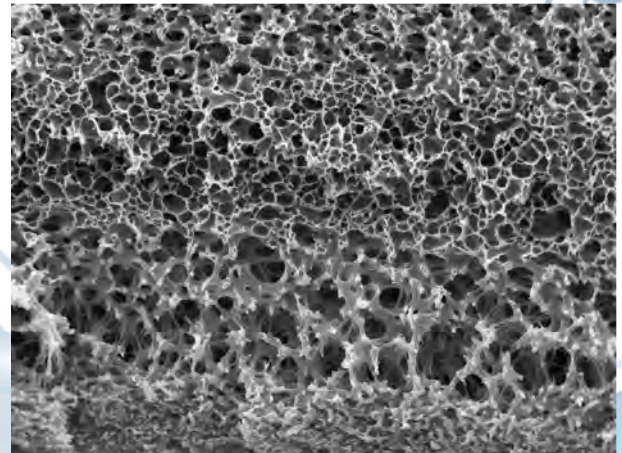
Multi-Layer Paint Coating

Advantages:

- Specific areas in electronic package devices can be sectioned and examined
- Thicknesses and homogeneity of layers can be illustrated quickly
- Alloys and interior grain structure in metallic samples can be documented with etches and preferential dyes
- Multi-layer printing and coating samples can be examined to check for bonding and lamination continuity
- Polymers can be sectioned and polished in order to determine interior consistency in formation
- Packaged devices are sectioned at key points to document mechanical or wire bonds and perform detailed failure analysis

Application Fields:

- Manufacturing Technologies
- Electronic Packages
- Semi-Conductor Design
- Construction and Coating Technologies
- Printing and Paper Processing
- Metallography
- Mineralogy and Geology
- Composite Environmental Analysis



Porous Filtration Membrane

Learn more at <http://www.MicroVisionLabs.com>